



Machine building driven by passion



Only Geringer customers have this advantage: so take advantage of our competence in machine building to put your special requirements into practice.





Fully automatic inline wafer retaping system UKA300





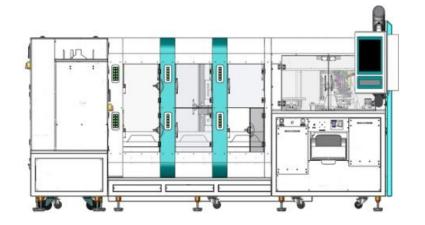
The UKA 300 is a flexible, fully automatic in-line wafer retaping system for wafers up to 6" in diameter.

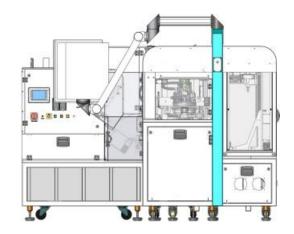
- Automatic frame handling system
- Magazining system
- Frames out of magazines or optional Framemounter
- Two frame sizes automatically processable (8" frames and 10" frames)
- Automatic foil cutting out of frame or frame with grip ring
- Automatic wafer transport to processstation
- Laminating bubblefree by vacuum process
- Automatic waste foil removal
- Frame barcode scanning
- Different kind of foils processable





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Technical Data	
Wafer frames	Two frame sizes automatically processable (8" frames and 10" frames)
Applicable target films	SWT10+, SWT20+, G965, UV-670D, UV-410T, NWS-Y12MS, Hitachi 1503 from roll
Mounted wafer frame source	industry standard wafer cassettes, automatic change over
Frame/Wafer identification	barcode reader for wafer frame (smart label optional)
Wafer sizes	2 inches up to 6 inches in diameter
Lamination method	vacuum
Remounted wafer output	on frame in industry standard wafer cassettes, automatic change over
Possitioning accuracy	X/Y direction: better than \pm 1mm; rotation: better than \pm 1°
Chip loss	≤ 0.5%
Chip offset	≤ 5% in relation to edge length
Breakage rate	≤ 1%
Bubbles	< 1% between wafer and film
Capacity	up to 50 wafers/hour
Dimensions, weight (approx.)	2,434mm x 3,520mm x 1,670mm (width x length x height) excluding jib-arm and operation panel, 2,500kg





Recommended Tabletop equipment for manual processes



Wafer delamination system



Wafer expanding system



Wafer laminating system





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Thank you